



SLOVENSKI STANDARD
SIST EN 61837-2:2001
01-september-2001

Surface mounted piezoelectric devices for frequency control and selection - Standard outlines and terminal lead connections - Part 2: Ceramic enclosures (IEC 61837-2:2000)

Surface mounted piezoelectric devices for frequency control and selection - Standard outlines and terminal lead connections -- Part 2: Ceramic enclosures

Oberflächenmontierbare piezoelektrische Bauteile zur Frequenzstabilisierung und - Selektion - Norm-Gehäusemaße und Anschlüsse -- Teil 2: Keramikgehäuse
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Dispositifs piézoélectriques à montage en surface pour la commande et le choix de la fréquence - Encombrements normalisés et connexions des sorties -- Partie 2: Enveloppes en céramique
SIST EN 61837-2:2001
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Ta slovenski standard je istoveten z: EN 61837-2:2000

ICS:

31.140 Úa: [^|\ dã } ^/ã
åã | \ dã } ^/ã | æ^ Piezoelectric and dielectric devices

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EUROPEAN STANDARD

EN 61837-2

NORME EUROPÉENNE

EUROPÄISCHE NORM

November 2000

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English version

**Surface mounted piezoelectric devices
for frequency control and selection -
Standard outlines and terminal lead connections
Part 2: Ceramic enclosures
(IEC 61837-2:2000)**

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This European Standard was approved by CENELEC on 2000-09-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Czech Republic, Denmark, Finland, France, Germany, Greece, Iceland, Ireland, Italy, Luxembourg, Netherlands, Norway, Portugal, Spain, Sweden, Switzerland and United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 49/461/FDIS, future edition 1 of IEC 61837-2, prepared by IEC TC 49, Piezoelectric and dielectric devices for frequency control and selection, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 61837-2 on 2000-09-01.

This publication is to be read in conjunction with EN 61240.

The following dates were fixed:

- latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2001-06-01
- latest date by which the national standards conflicting with the EN have to be withdrawn (dow) 2003-09-01

Annexes designated "normative" are part of the body of the standard.

Annexes designated "informative" are given for information only.

In this standard, annex ZA is normative and annex A is informative.

Annex ZA has been added by CENELEC.

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The text of the International Standard IEC 61837-2:2000 was approved by CENELEC as a European Standard without any modification.

[SIST EN 61837-2:2001](http://standards.iteh.ai/catalog/standards/sist-en-61837-2-2001)

In the official version for annex A Bibliography, the following notes have to be added for the standards indicated:

- | | |
|---------------|---|
| IEC 60368-1 | NOTE: Harmonized as EN 60368-1:2000 (not modified). |
| IEC 60368-2-2 | NOTE: Harmonized as EN 60368-2-2:1999 (not modified). |
| IEC 60679-1 | NOTE: Harmonized as EN 60679-1:1998 (not modified). |
-

Annex ZA
(normative)**Normative references to international publications
with their corresponding European publications**

This European Standard incorporates by dated or undated reference, provisions from other publications. These normative references are cited at the appropriate places in the text and the publications are listed hereafter. For dated references, subsequent amendments to or revisions of any of these publications apply to this European Standard only when incorporated in it by amendment or revision. For undated references the latest edition of the publication referred to applies (including amendments).

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61240	1994	Piezoelectric devices - Preparation of outline drawings of surface-mounted devices (SMD) for frequency control and selection - General rules	EN 61240	1997

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**NORME
INTERNATIONALE
INTERNATIONAL
STANDARD**

**CEI
IEC**

61837-2

Première édition
First edition
2000-08

**Dispositifs piézoélectriques à montage en surface
pour la commande et le choix de la fréquence –
Encombres normalisés et connexions
des sorties –**

**Partie 2:
Enveloppes en céramique**

**Surface mounted piezoelectric devices
for frequency control and selection –
Standard outlines and terminal lead connections –**

**Part 2:
Ceramic enclosures**

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International Electrotechnical Commission
Telefax: +41 22 919 0300

3, rue de Varembe Geneva, Switzerland
e-mail: inmail@iec.ch IEC web site <http://www.iec.ch>



Commission Electrotechnique Internationale
International Electrotechnical Commission
Международная Электротехническая Комиссия

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SURFACE MOUNTED PIEZOELECTRIC DEVICES
FOR FREQUENCY CONTROL AND SELECTION –
STANDARD OUTLINES AND TERMINAL LEAD CONNECTIONS –**

Part 2: Ceramic enclosures

FOREWORD

- 1) The IEC (International Electrotechnical Commission) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of the IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, the IEC publishes International Standards. Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. The IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of the IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested National Committees.
- 3) The documents produced have the form of recommendations for international use and are published in the form of standards, technical specifications, technical reports or guides and they are accepted by the National Committees in that sense.
- 4) In order to promote international unification, IEC National Committees undertake to apply IEC International Standards transparently to the maximum extent possible in their national and regional standards. Any divergence between the IEC Standard and the corresponding national or regional standard shall be clearly indicated in the latter.
- 5) The IEC provides no marking procedure to indicate its approval and cannot be rendered responsible for any equipment declared to be in conformity with one of its standards.
- 6) Attention is drawn to the possibility that some of the elements of this International Standard may be the subject of patent rights. The IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 61837-2 has been prepared by IEC technical committee 49: Piezoelectric and dielectric devices for frequency control and selection.

This standard shall be read in conjunction with IEC 61240.

The text of this standard is based on the following documents:

FDIS	Report on voting
49/461/FDIS	49/471/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 3.

Annex A is for information only.

IEC 61837 consists of the following parts, under the general title: *Surface mounted piezoelectric devices for frequency control and selection – Standard outlines and terminal lead connections*

- Part 1: Plastic moulded enclosure outlines;
- Part 2: Ceramic enclosures;
- Part 3: Metal enclosures.

The committee has decided that the contents of this publication will remain unchanged until 2005. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

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INTRODUCTION

The demand for surface-mounted devices (SMD) for frequency control and selection increases every year, and IEC 61240 has been prepared in response to this demand. It has been necessary to prepare separate standards covering individual SMD outlines and terminal lead connections based on the general rules in IEC 61240.

After considerable discussion on this matter at the TC 49 meeting in Rotterdam, it has been decided that the individual SMDs available should be separated into three parts depending on the material used to fabricate the enclosure. A distinction is made between

- plastic moulded enclosures, which are dealt with in IEC 61837-1;
- ceramic enclosures, which are dealt with in this standard; and
- metal enclosures, which are dealt with in IEC 61837-3.

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SURFACE MOUNTED PIEZOELECTRIC DEVICES FOR FREQUENCY CONTROL AND SELECTION – STANDARD OUTLINES AND TERMINAL LEAD CONNECTIONS –

Part 2: Ceramic enclosures

1 Scope

This part of IEC 61837 deals with standard outlines and terminal lead connections as they apply to SMDs for frequency control and selection in ceramic enclosures, and is based on IEC 61240.

2 Normative references

The following normative documents contain provisions which, through reference in this text, constitute provisions of this part of IEC 61837. For dated references, subsequent amendments to, or revisions of, any of these publications do not apply. However, parties to agreements based on this part of IEC 61837 are encouraged to investigate the possibility of applying the most recent editions of the normative documents indicated below. For undated references, the latest edition of the normative document referred to applies. Members of IEC and ISO maintain registers of currently valid International Standards.

IEC 61240:1994, *Piezoelectric devices – Preparation of outline drawings of surface-mounted devices (SMD) for frequency control and selection – General rules*

<https://standards.iteh.ai/catalog/standards/sist/71f64dd4-10ec-4a1a-8df8-b9be6244a726/sist-en-61837-2-2001>

3 Configuration of enclosures

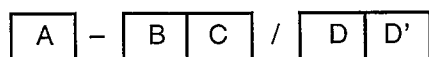
The enclosures of surface-mounted devices are made of ceramic materials with the terminals of deposited metal film (leadless type) based on Descriptive designation system for semiconductors – Devices package.

The configuration symbols are as shown below.

- DCC (dual chip carrier);
- QCC (quad chip carrier).

4 Designation of types

The designation of types is shown on the four parts as follows:



A: Configuration symbol of enclosures:

- DCC (dual chip carrier);
- QCC (quad chip carrier).

B: Structure of terminal leads: leadless type has no mark.

C: Number of terminal leads.

D: Serial number of both figures.

5 Ceramic enclosure dimensions

The dimensions given in this standard apply to all completed SMD-devices for frequency control and selection. Only those dimensions are given which meet the requirements of IEC 61240.

6 Lead connections

Recommendations for the lead connections of all completed SMD-devices for frequency control and selection are given in the following individual sheets. Lead connections shall always be given in the detail specification.

7 Designation of ceramic enclosures

The following table sets out the designation of the ceramic enclosures, as outlined in the ensuing specification sheets.

Table 1 – Designation of ceramic enclosures

No.	Type	Sheet no.	Description
1	DCC-6/01	Sheet 1	Ceramic, welded, six leadless SMD outline
2	DCC-4/01	Sheet 2	Ceramic, four leadless SMD outline
3	DCC-4/02	Sheet 3	Ceramic, welded, four leadless SMD outline
4	DCC-4/03		
5	DCC-4/04	Sheet 4	Ceramic, welded, four leadless SMD outline
6	DCC-4/05		
7	DCC-4/06	Sheet 5	Ceramic, welded, four leadless SMD outline
8	DCC-4/07		
9	DCC-2/01	Sheet 6	Ceramic, two leadless SMD outline
10	DCC-2/02	Sheet 7	Ceramic, two leadless SMD outline
11	QCC-18/01	Sheet 8	Ceramic, welded, 18 leadless SMD outline
12	QCC-12/01	Sheet 9	Ceramic, welded, 12 leadless SMD outline
13	QCC-12/02	Sheet 10	Ceramic, welded, 12 leadless SMD outline
14	QCC-10/01	Sheet 11	Ceramic, welded, 10 leadless SMD outline
15	QCC-8/01	Sheet 12	Ceramic, welded, eight leadless SMD outline
16	QCC-8/02	Sheet 13	Ceramic, welded, eight leadless SMD outline
17	QCC-6/01	Sheet 14	Ceramic, welded, six leadless SMD outline
18	QCC-6/02		
19	DCC-4/08	Sheet 15	Ceramic, welded, four leadless SMD outline